

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2983	(hydrophilic) and wafer and bonding	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:37
L2	4264	(hydrophilic or hydrophobic) and wafer and bonding	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:37
L3	650	(hydrophilic or hydrophobic).clm. and wafer and bonding	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:37
L4	594113	(hydrophilic or hydrophobic).clm. and wafer ".clm.and" bonding	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:38
L5	48	(hydrophilic or hydrophobic).clm. and wafer.clm. and bonding.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:38
L6	31	(hydrophilic or hydrophobic).clm. and wafer.clm. and bonding.clm. and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:38
L7	21	(hydrophilic or hydrophobic).clm. and wafer.clm. and bonding.clm. and semiconductor.clm. and layer.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:39
L8	9	(hydrophilic or hydrophobic).clm. and wafer.clm. and bonding.clm. and semiconductor.clm. and layer.clm. and (crystal or crystalline or crystallographic).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:40
L9	5	(hydrophilic or hydrophobic).clm. and wafer.clm. and bonding.clm. and semiconductor.clm. and layer.clm. and (crystal or crystalline or crystallographic).clm. and orientation.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:40

L10	0	interface.clm. and (hydrophilic or hydrophobic).clm. and wafer.clm. and bonding.clm. and semiconductor.clm. with layer.clm. with (crystal or crystalline or crystallographic).clm. with orientation.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:41
L11	0	(hydrophilic or hydrophobic).clm. with semiconductor.clm. with layer.clm. with (crystal or crystalline or crystallographic).clm. with orientation.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:41
L12	0	(hydrophilic or hydrophobic) with semiconductor with layer with (crystal or crystalline or crystallographic) with orientation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:41
L13	2	(semiconductor adj layer) with (interface) with (hydrophobic or hydrophilic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:43
L14	578	(layer) with (interface) with (hydrophobic or hydrophilic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:44
L15	52	((layer) with (interface) with (hydrophobic or hydrophilic)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:44
L16	5	((layer) with (interface) with (hydrophobic or hydrophilic)).clm. and (crystal or crystalline or crystallographic).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:45
L17	1	((layer) with (interface) with (hydrophobic or hydrophilic)).clm. and (crystal or crystalline or crystallographic).clm. and (direct near5 bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:47
L18	0	((layer) near10 (interface) near10 (hydrophobic or hydrophilic)).clm. and (crystal or crystalline or crystallographic).clm. and (direct near5 bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:47
L19	4	((layer) near10 (interface) near10 (hydrophobic or hydrophilic)).clm. and (crystal or crystalline or crystallographic).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:48

L20	3	((layer) near10 (interface) near10 (hydrophobic or hydrophilic)).clm. and (crystal or crystalline or crystallographic).clm. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 08:48
L21	3	((layer) near10 (interface) near10 (hydrophobic or hydrophilic)).clm. and (crystal or crystalline or crystallographic).clm. and (wafer near2 bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 10:33
L22	4	((layer) near10 (interface) near10 (hydrophobic or hydrophilic)) and (crystal or crystalline or crystallographic).clm. and (wafer near2 bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/21 10:34